

DATA SHEET

Part No.	AN26113A
Package Code No.	ULGA006-F-1517A

Contents

■ Overview	3
■ Features	3
■ Applications	3
■ Package	3
■ Type	3
■ Application Circuit Example (Block Diagram)	4
■ Pin Descriptions	5
■ Absolute Maximum Ratings	6
■ Operating Supply Voltage Range	6
■ Allowable Voltage Range	7
■ Electrical Characteristics	8
■ Technical Data	10
• $P_D - T_a$ diagram	10
■ Usage Notes	11

AN26113A

Splitter Amplifier IC for VHF & UHF Band (40 MHz to 900 MHz) Applications

■ Overview

- AN26113A is a splitter amplifier IC for VHF and UHF band (40 MHz to 900 MHz) applications.
- Realizing high performance by using 0.30 μm Bi-CMOS process ($f_T = 20 \text{ GHz}$, $f_{\text{max}} = 20 \text{ GHz}$).
- Achieving miniaturization by using small size package.

■ Features

- 1-IN, 2-OUT active splitter
- Operation voltage +3.30 V typ.
- Current consumption 130 mA typ.
- Controllable gain 11.0 dB typ. $f_{\text{RX}} = 550 \text{ MHz}$, $Z_0 = 50 \Omega$
- Low noise figure 4.0 dB typ. $f_{\text{RX}} = 550 \text{ MHz}$, $Z_0 = 50 \Omega$ (High-Gain mode)
- Low distortion +13.0 dBm typ. $f_{\text{RX}} = 550 \text{ MHz}$, $Z_0 = 50 \Omega$ (High-Gain mode)
(IIP3 +10 MHz offset)
- Small package (6-pin plastic package)

■ Applications

- VHF & UHF band (40 MHz to 900 MHz) applications

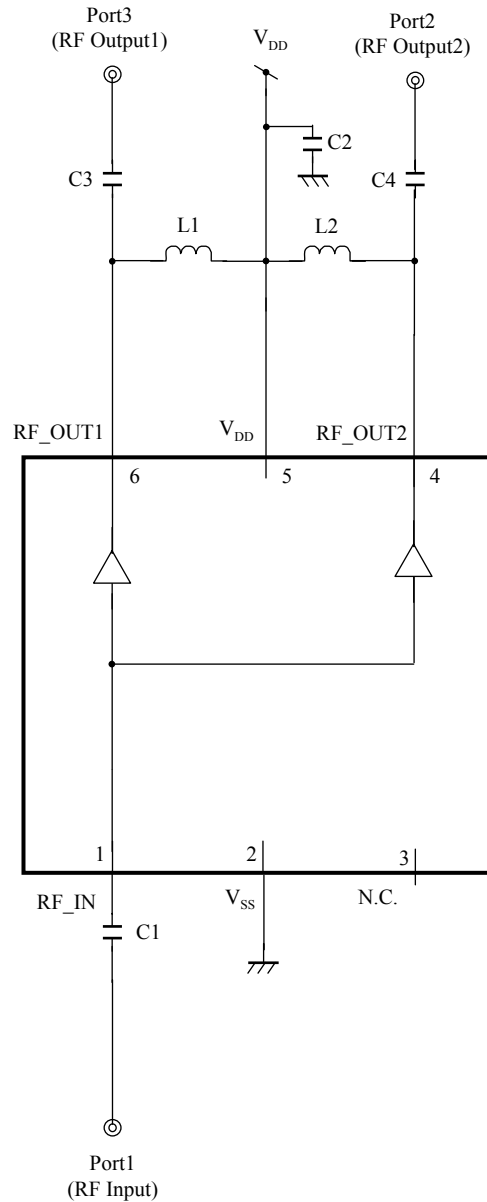
■ Package

- 6 pin Fine Pitch Land Grid Array Package (LGA Type)
Size : 1.52 mm \times 1.72 mm \times 0.40 mm

■ Type

- Bi-CMOS IC

■ Application Circuit Example (Block Diagram)



- Notes)
- This application circuit is an example. The operation of mass production set is not guaranteed. You should perform enough evaluation and verification on the design of mass production set. You are fully responsible for the incorporation of the above application circuit and information in the design of your equipment.
 - This block diagram is for explaining functions. Part of the block diagram may be omitted, or it may be simplified.

■ Pin Descriptions

Pin No.	Pin name	Type	Description
1	RF_IN	Input	RF input
2	V _{SS}	Ground	V _{SS}
3	N.C.	—	—
4	RF_OUT2	Output	RF output2
5	V _{DD}	Power supply	V _{DD}
6	RF_OUT1	Output	RF output1

■ Absolute Maximum Ratings

Note) Absolute maximum ratings are limit values which do not result in damages to this IC, and IC operation is not guaranteed at these limit values.

A No.	Parameter	Symbol	Rating	Unit	Notes
1	Supply voltage	V_{DD}	3.6	V	*1
2	Supply current	I_{DD}	—	A	—
3	Power dissipation	P_D	83.0	mW	*2
4	Operating ambient temperature	T_{opr}	-20 to +80	°C	*3
5	Storage temperature	T_{stg}	-40 to +150	°C	*3

Notes) *1 : The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

*2 : The power dissipation shown is the value at $T_a = 80^\circ\text{C}$ for the independent (unmounted) IC package without a heat sink.

When using this IC, refer to the $\bullet P_D$ - T_a diagram in the ■ Technical Data standard and design the heat radiation with sufficient margin so that the allowable value might not be exceeded based on the conditions of power supply voltage, load, and ambient temperature.

*3 : Except for the power dissipation, operating ambient temperature, and storage temperature, all ratings are for $T_a = 25^\circ\text{C}$.

■ Operating Supply Voltage Range

Parameter	Symbol	Range	Unit	Notes
Supply voltage range	V_{DD}	3.13 to 3.47	V	*1

Notes) *1 : The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

■ Allowable Voltage Range

- Notes)
- Allowable current and voltage ranges are limit ranges which do not result in damages to this IC, and IC operation is not guaranteed within these limit ranges.
 - Voltage values are with respect to the GND.
 - Applying external voltage to any pin not mentioned below leads to the malfunction and the damage of the device.
 - Below ratings are specified for prevention of malfunction and stress, not for guaranteed operation.

Pin No.	Pin name	Rating	Unit	Notes
1	RF_IN	—	V	*1
4	RF_OUT2	-0.3 to ($V_{DD}+0.3$)	V	*2, *3
6	RF_OUT1	-0.3 to ($V_{DD}+0.3$)	V	*2, *3

Notes) *1 : RF signal input pin. (Maximum input power is +17dBm.) Do not apply DC current.

*2 : RF signal output pin. Do not apply DC current.

*3 : ($V_{DD} + 0.3$) V must not be exceeded 3.6 V

■ Electrical Characteristics at $V_{DD} = 3.30\text{ V}$ Note) $T_a = 25^\circ\text{C} \pm 2^\circ\text{C}$ unless otherwise specified.

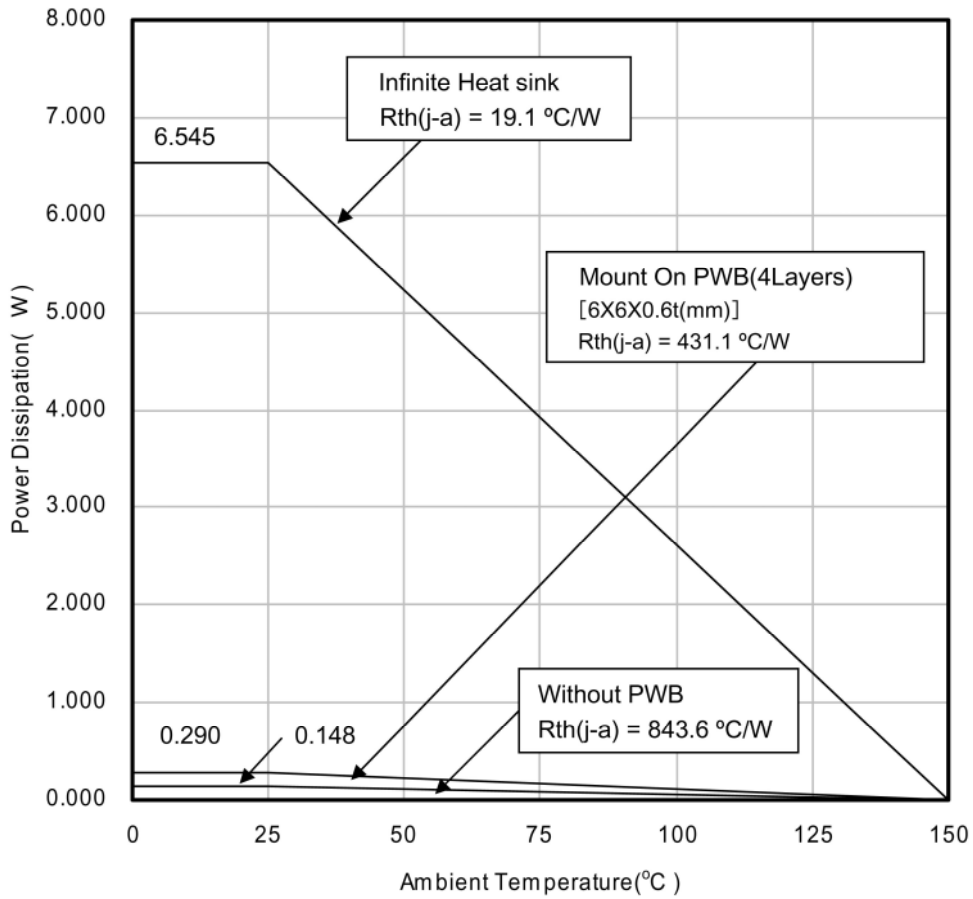
B No.	Parameter	Symbol	Conditions	Limits			Unit	Notes
				Min	Typ	Max		
DC Electrical Characteristics								
DC-1	Supply current	I_{DD}	V_{DD} current No input signal	90	130	175	mA	—

■ Electrical Characteristics (continued) at $V_{DD} = 3.30\text{ V}$

Note) $T_a = 25^\circ\text{C} \pm 2^\circ\text{C}$, $f_{RX} = 550\text{ MHz}$, $PRX = -20\text{ dBm}$, $Z_0 = 50\ \Omega$, CW unless otherwise specified.

B No.	Parameter	Symbol	Conditions	Limits			Unit	Notes
				Min	Typ	Max		
Splitter Amplifier AC Electrical Characteristics								
A-1	Power gain	GHS	High-gain mode $f = f_{RX}$	11.2	13.2	15.2	dB	—
A-2	IIP3 + 10 MHz offset	IIP3H1S	High-gain mode $f_1 = f_{RX}$ $f_2 = f_{RX} + 10\text{ MHz}$ Input 2 signals (f_1, f_2)	8.2	12.2	—	dBm	—

- Technical Data
- $P_D - T_a$ diagram



■ Usage Notes**• Special attention and precaution in using**

1. This IC is intended to be used for general electronic equipment [Television set].

Consult our sales staff in advance for information on the following applications:

- Special applications in which exceptional quality and reliability are required, or if the failure or malfunction of this IC may directly jeopardize life or harm the human body.
- Any applications other than the standard applications intended.
 - (1) Space appliance (such as artificial satellite, and rocket)
 - (2) Traffic control equipment (such as for automobile, airplane, train, and ship)
 - (3) Medical equipment for life support
 - (4) Submarine transponder
 - (5) Control equipment for power plant
 - (6) Disaster prevention and security device
 - (7) Weapon
 - (8) Others : Applications of which reliability equivalent to (1) to (7) is required

It is to be understood that our company shall not be held responsible for any damage incurred as a result of or in connection with your using the IC described in this book for any special application, unless our company agrees to your using the IC in this book for any special application.

2. Pay attention to the direction of LSI. When mounting it in the wrong direction onto the PCB (printed-circuit-board), it might smoke or ignite.
3. Pay attention in the PCB (printed-circuit-board) pattern layout in order to prevent damage due to short circuit between pins. In addition, refer to the Pin Description for the pin configuration.
4. Perform a visual inspection on the PCB before applying power, otherwise damage might happen due to problems such as a solder-bridge between the pins of the semiconductor device. Also, perform a full technical verification on the assembly quality, because the same damage possibly can happen due to conductive substances, such as solder ball, that adhere to the LSI during transportation.
5. Take notice in the use of this product that it might break or occasionally smoke when an abnormal state occurs such as output pin- V_{CC} short (Power supply fault), output pin-GND short (Ground fault), or output-to-output-pin short (load short) .
And, safety measures such as an installation of fuses are recommended because the extent of the above-mentioned damage and smoke emission will depend on the current capability of the power supply.
6. When designing your equipment, comply with the range of absolute maximum rating and the guaranteed operating conditions (operating power supply voltage and operating environment etc.). Especially, please be careful not to exceed the range of absolute maximum rating on the transient state, such as power-on, power-off and mode-switching. Otherwise, we will not be liable for any defect which may arise later in your equipment.
Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
7. When using the LSI for new models, verify the safety including the long-term reliability for each product.
8. When the application system is designed by using this LSI, be sure to confirm notes in this book.
Be sure to read the notes to descriptions and the usage notes in the book.

Request for your special attention and precautions in using the technical information and semiconductors described in this book

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- (5) When designing your equipment, comply with the range of absolute maximum rating and the guaranteed operating conditions (operating power supply voltage and operating environment etc.). Especially, please be careful not to exceed the range of absolute maximum rating on the transient state, such as power-on, power-off and mode-switching. Otherwise, we will not be liable for any defect which may arise later in your equipment.
Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
- (6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.
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